



Standard Cell Layout Generation: Review, Challenges, and Future Works

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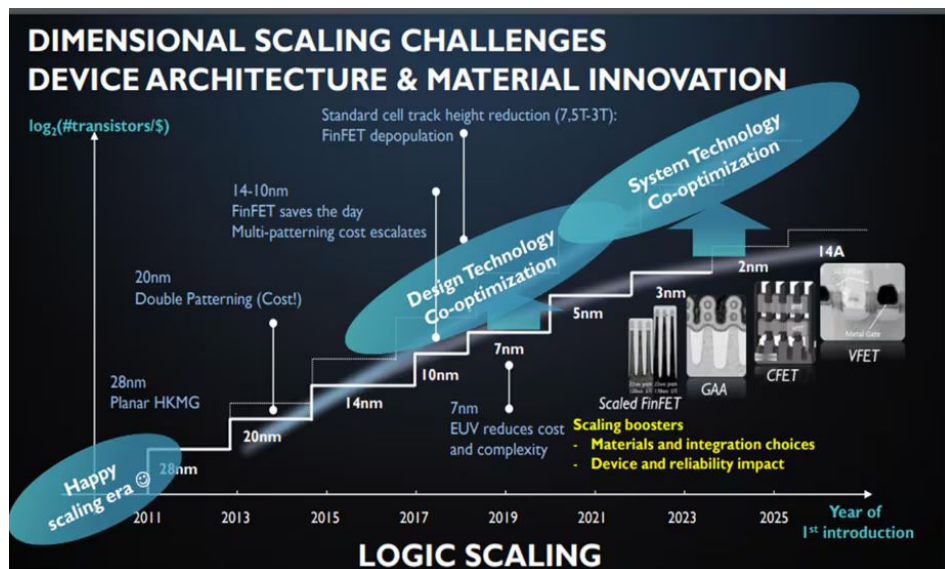


Outlines

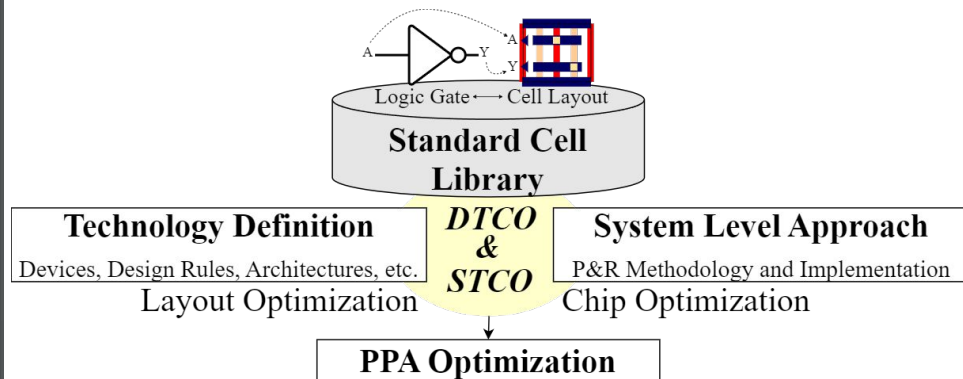
- 1. Motivation**
- 2. Review : Placement and Routing with Tool Sets**
- 3. Challenges : Complexity and Optimality**
- 4. Future Works : Optimization and New Devices**
- 5. Conclusion**

Motivation: Relentless Demand for Scaling

- Standard cells are one pivotal brick for chip power, performance, and area (PPA) scaling

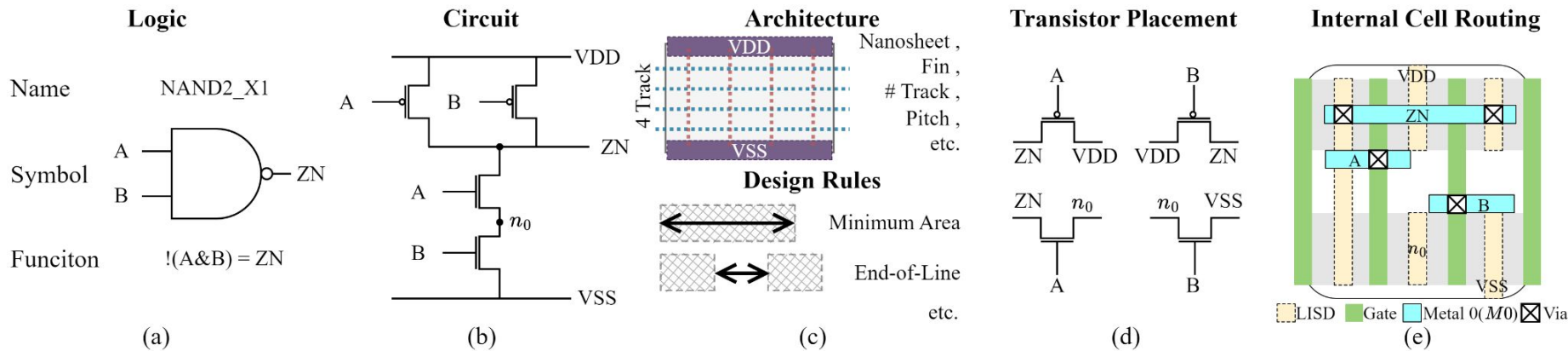


IMEC logic scaling loadmap



Motivation: Standard Cell Design Flow

- NP-complete with limited problem sizes



Review : Cell Layout Automation

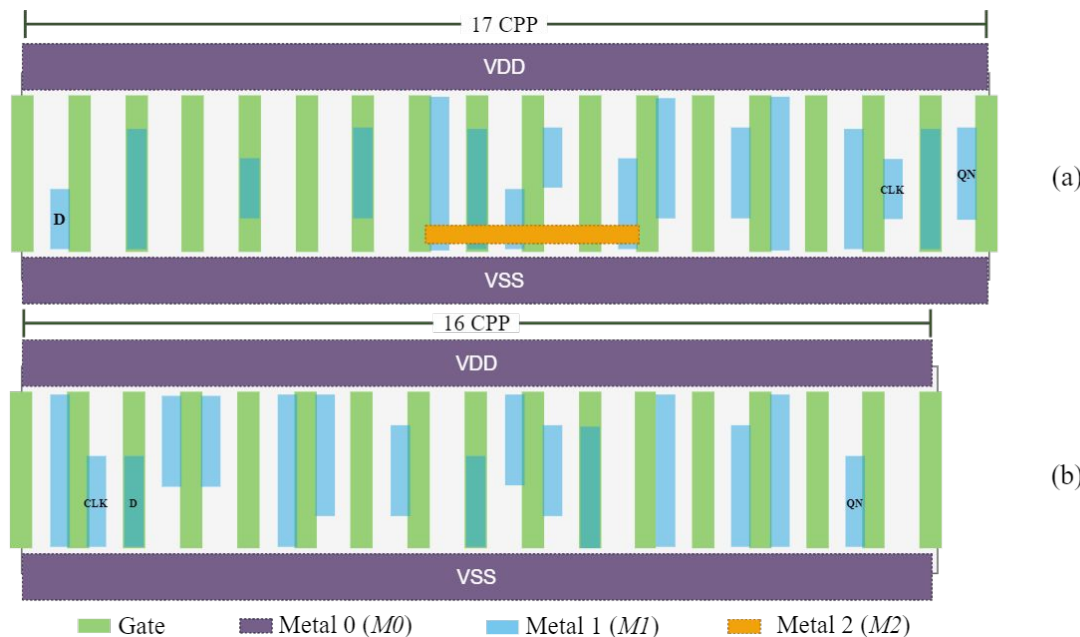
- Cell generators for sub-10nm node covering placement and routing

	Algorithms		Optimality (✓: meets criteria, —: bounded by constraints)					Support	
Tool	Placement	Routing	wo pre T.pair	wo T.part	T.P w rp	I.C.R w pa	runtime	DRs	Metal
NCTUCell [15]	DP	ILP	—	✓	✓	—	<90sec.(FF)	7nm [8]	bi
BonnCell [27]	S-Tree	MIP	✓	✓	✓	✓	<8hr.(FF)	7nm	uni
SP&R [12]	SMT	SMT	✓	—	✓	✓	<1hr.(FF)	7nm	uni
MCell [14]	A*	MAX-SAT	—	—	✓	—	<81min.(4BFF)	7nm	bi
NVCell [22]	SA, RL	GA, RL	✓	—	✓	✓	N/P	~5nm	uni
itplace [13]	S-Tree, CNN	ILP [15]	✓	—	✓	—	N/P	7nm	bi
CSyn-fp [3]	S-Tree	SMT [12]	—	—	✓	✓	<18min.(FF)	7nm	bi
SMTCell [6]	SMT	SMT	✓	—	✓	✓	<94min.(LHQ)	3nm [24]	uni

Table 1: Comparison of cell layout generation tools based on their algorithms and optimality criteria. Abbreviations are as follows: wo pre T.pair: without pre-transistor pairing, wo T.part: without transistor partitioning, T.P w rp: transistor placement with routing prediction, I.C.R w pa: internal cell routing with pin accessibility metric, DRs: supporting design rules, Metal: lowest metal's routing direction, N/P: Not Provided.

Challenges : Complexity & Optimality

- Transistor Partitioning
 - Reduces the search space
 - Misses the best solution



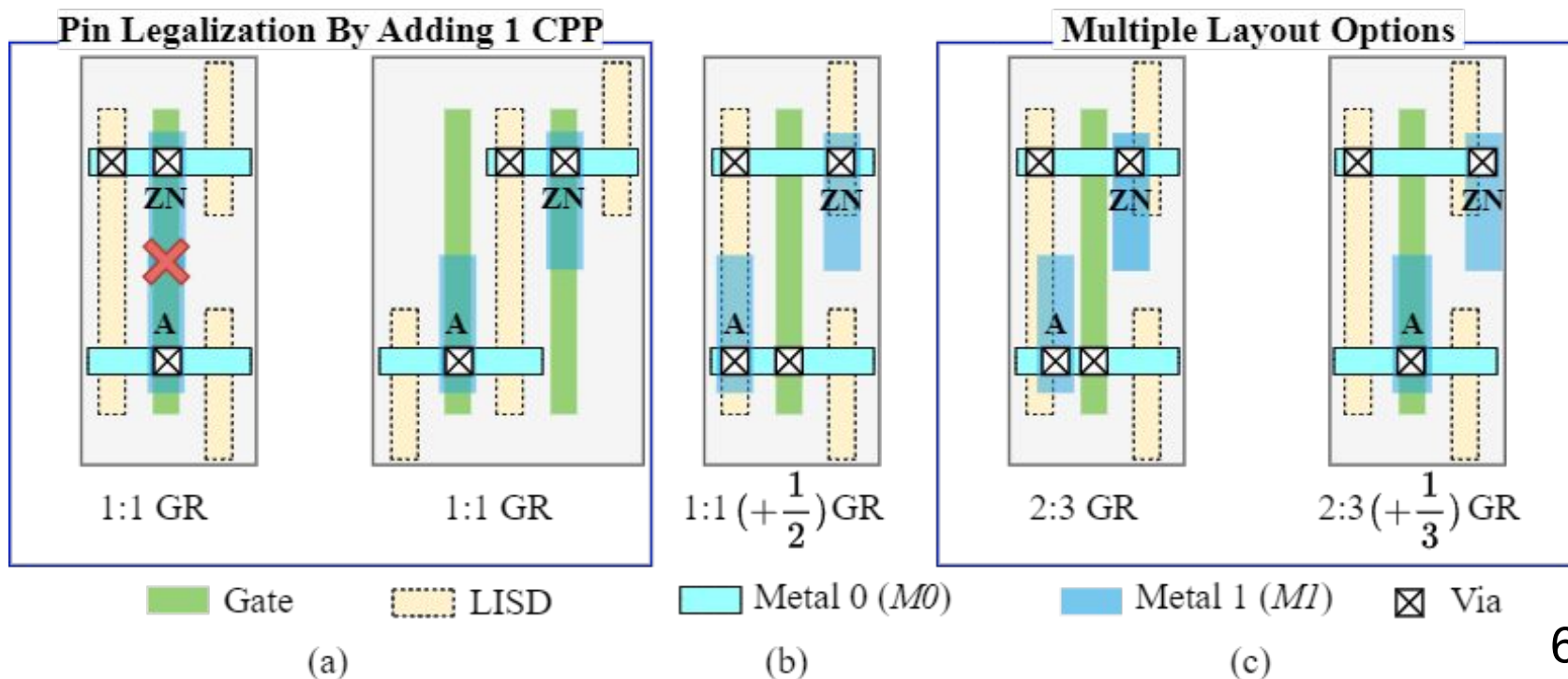
Design hierarchy
based partitioning
Fast / **Not optimal**

Exhaustive search
Slow / **Optimal**

Challenges : Complexity & Optimality

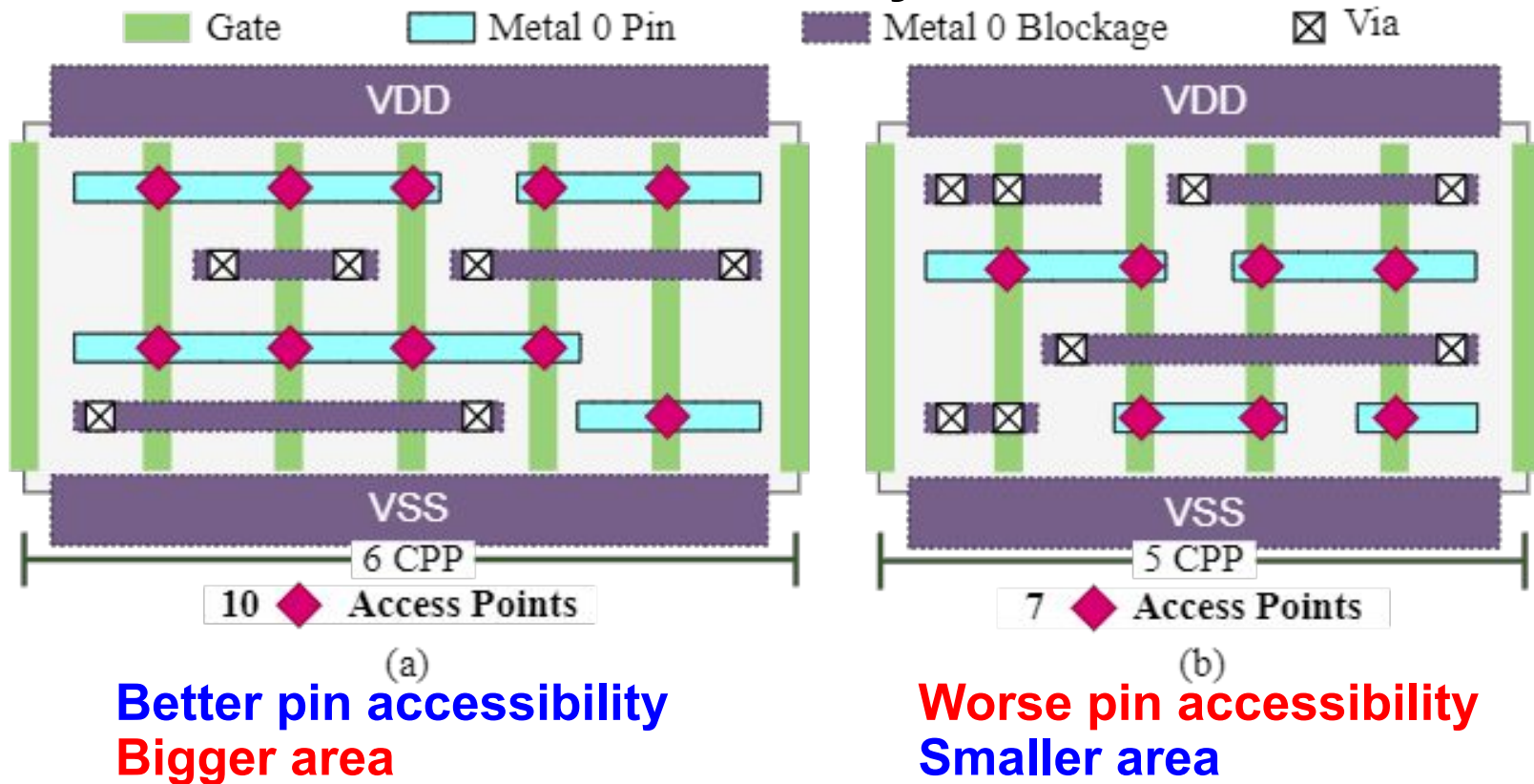
- **Gear Ratio & Offset**

- More routing resources with added complexity
- E.g. 2:3 GR spans a non-uniform grid



Challenges : Complexity & Optimality

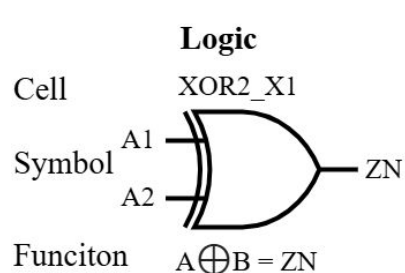
- Design Trade-offs
 - Cell Area vs Pin accessibility



Future Works: Optimization & New Devices

● Logic Optimization

- Expand search space for optimality
- Produce multiple design possibilities



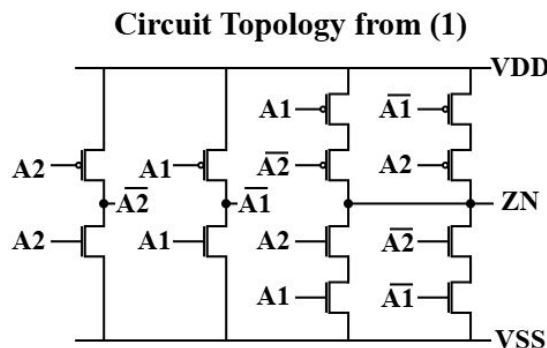
(a)

Truth Table & Boolean Equations

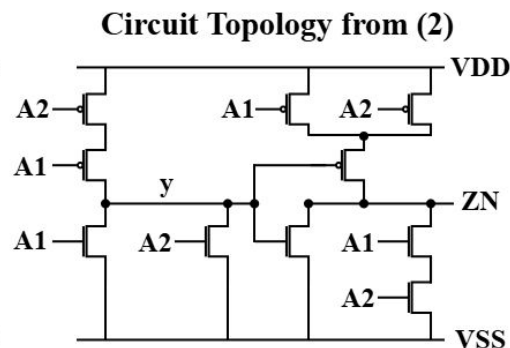
A1	A2	ZN
0	0	0
0	1	1
1	0	1
1	1	0

$ZN = \bar{A1} \cdot A2 + A1 \cdot \bar{A2}$ (1)
 $ZN = (\bar{y} + A1 \cdot A2)$ (2)
 $y = \overline{(A1 + A2)}$

(b)



(c)

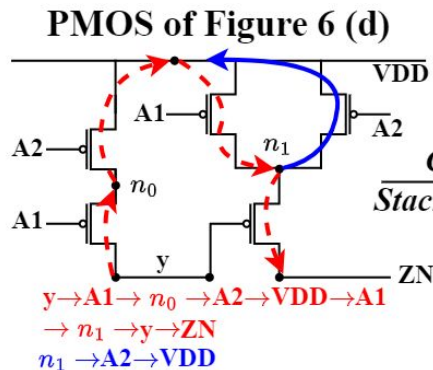
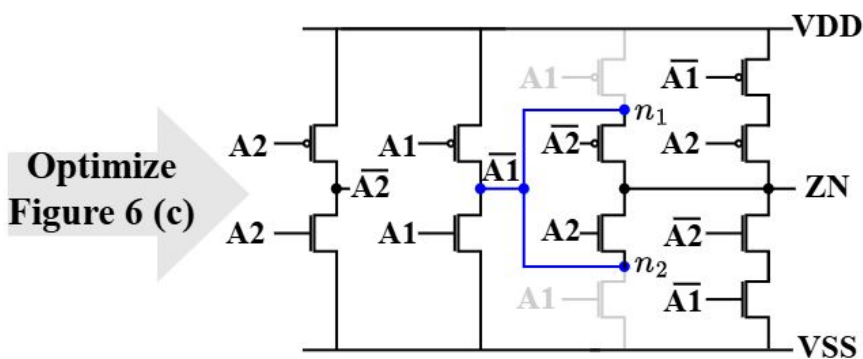


(d)

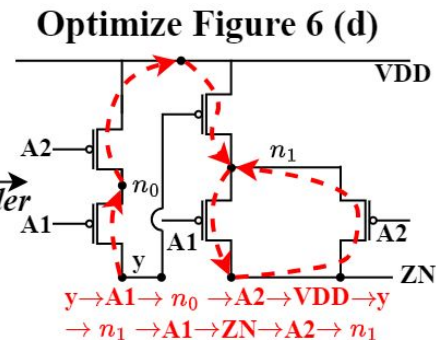
Future Works: Optimization & New Devices

- **Topology optimization - 1**

- Internal net state verification for transistor removal
- Changing stack order for better Euler path



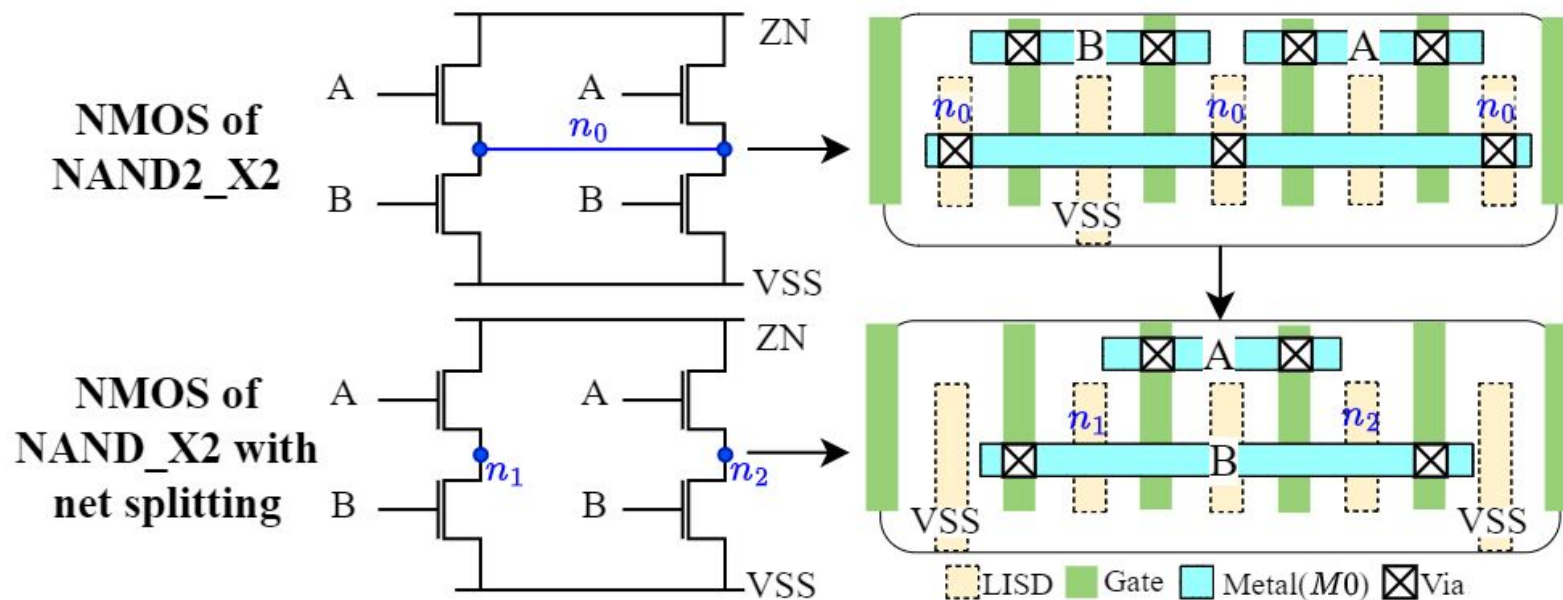
*Change
Stacking Order*



Future Works: Optimization & New Devices

- **Topology optimization - 2**

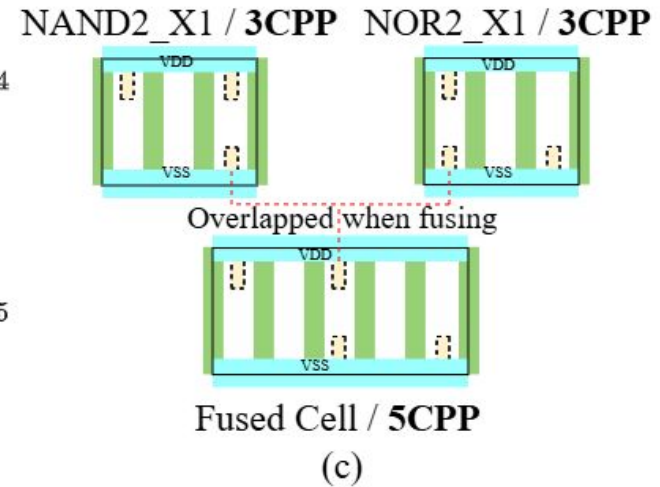
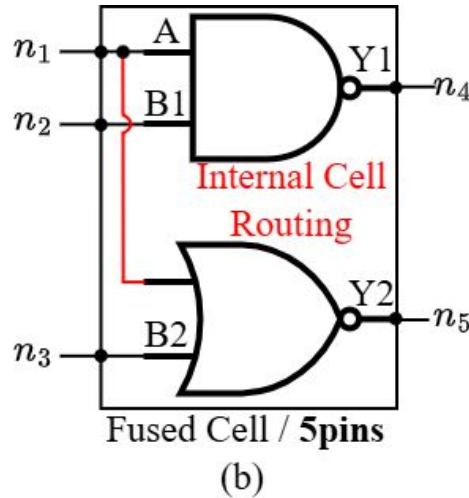
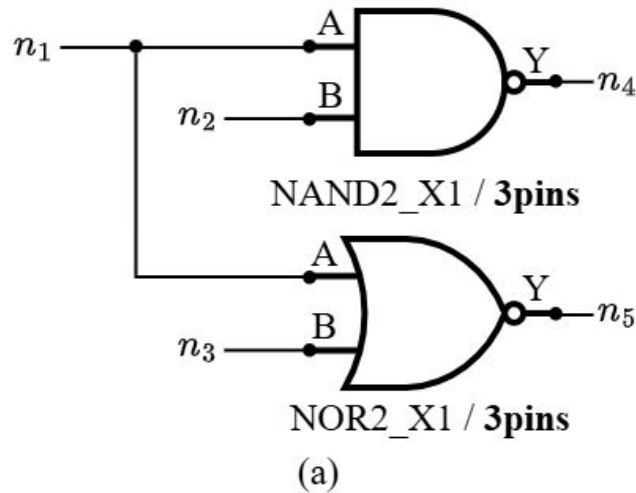
- Increasing the drive strength of cell differently
- Net splitting can improve circuit performance



Future Works: Optimization & New Devices

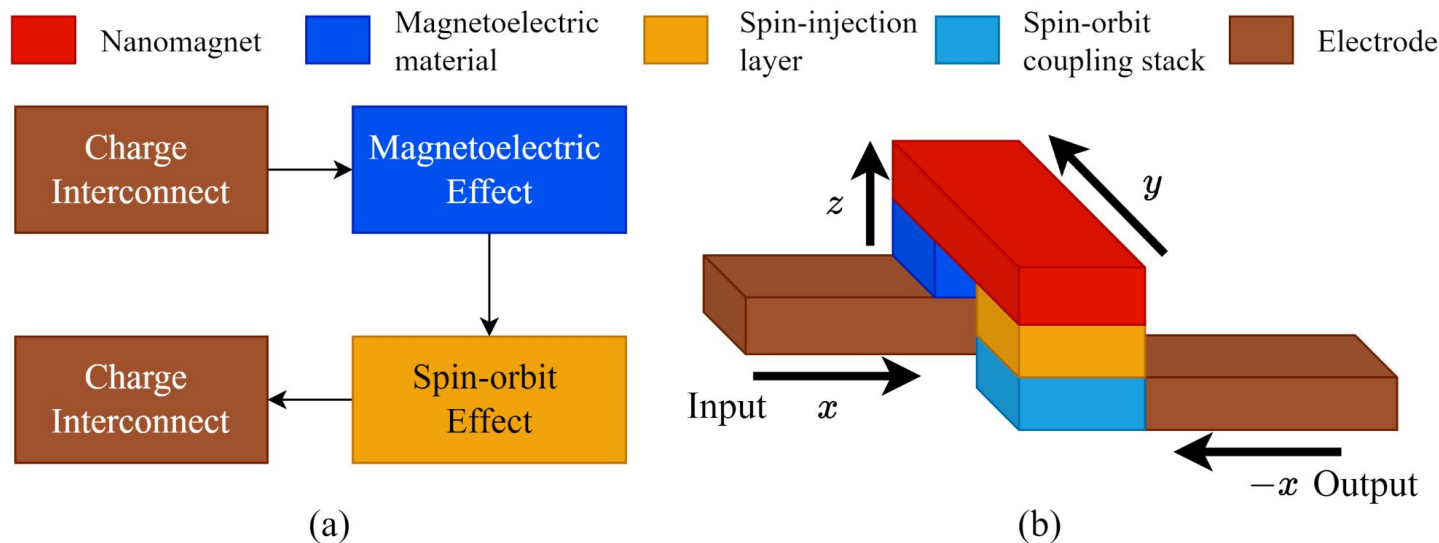
- **Standard cell fusion**

- Pin density wall
- Fused cell can reduce pin count and cell area



Future Works: Optimization & New Devices

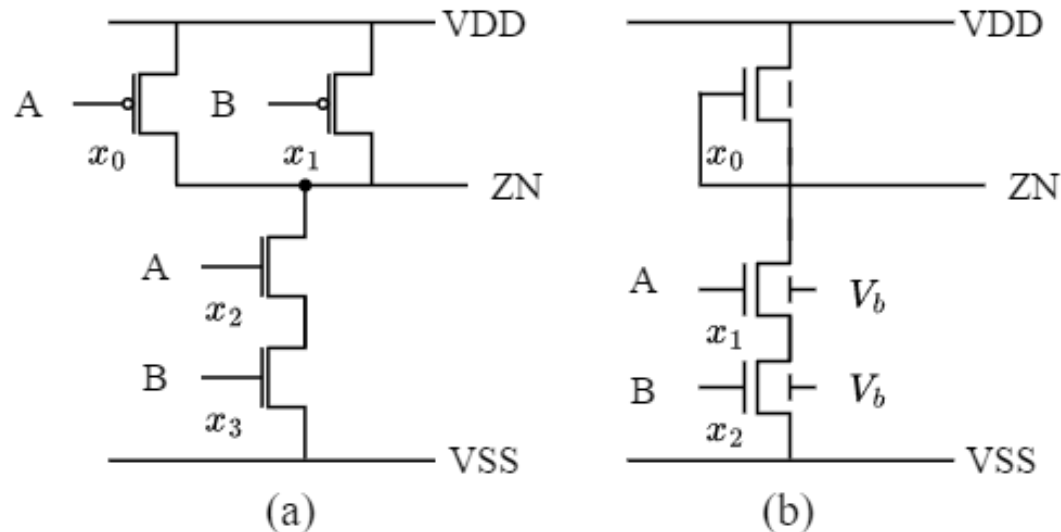
- **Magnetoelectric Spin–Orbit (MESO) Device**
 - Address the limitations of traditional CMOS scaling
 - Use the majority function and has a compatible process with current VLSI technology



Future Works: Optimization & New Devices

- **Thin Film Transistors (TFT)**

- **Widely adopted in digital displays and is being researched for low-cost logic circuit applications and low temperatures**
- **Only operate with n-channel logic**



Conclusion

- **NP-complete with limited problem sizes**
- **Payoff for PPA improvement**
- **DTCO/STCO + engineering R&D**
- **Larger scopes for further improvement**

Thank you!